

DIO59016 USB-Compliant Single-cell Li-Ion Switching Charger with USB-OTG Boost Regulator

Features

- Fully Integrated, High-Efficiency Charger for Single-Cell Li-Ion and Li-Polymer Battery Packs
- Faster Charging than Linear
- Charge Voltage Accuracy: 0.5% at 25°C 1% from 0 to 125°C
- ±7% Input Current Regulation Accuracy
- ±7% Charge Current Regulation Accuracy
- 26V Absolute Maximum Input Voltage
- 6V Maximum Input Operating Voltage
- 1.5A Maximum Charge Rate
- Programmable through High-Speed I²C Interface(3.4Mb/s) with Fast Mode Plus Compatibility
 - Input Current
 - Fast-Charge/Termination Current
 - Charger Voltage
 - Recharge Voltage
 - Termination Enable
- 2MHz Synchronous Buck PWM Controller with Wide Duty Cycle Range
- Small Footprint 1µH External Inductor
- 1.8V Regulated Output from VBUS for Auxiliary Circuits
- Dynamic Input Voltage Control
- Low Reverse Leakage to Prevent Battery Drain to VBUS
- 5V, 1A Boost Mode for USB OTG for 3.2V to 4.5V Battery Input
- Available in TQFN3*3-16, DFN3*3-12 Packages.

Descriptions

The DIO59016 combines a highly integrated switch-mode charger, to minimize single-cell Lithium-ion (Li-ion) charging time from a USB power source, and a boost regulator to power a USB peripheral from the battery.

The charging parameters and operating modes are programmable through an I²C Interface that operates up to 3.4Mbps. The charger and boost regulator circuits switch at 2MHz to minimize the size of external passive components.

The DIO59016 provides battery charging in three phases: conditioning, constant current and constant voltage.

To ensure USB compliance and minimize charging time, the input current limit can be changed through the I²C by the host processor. Charge termination is determined by a programmable minimum current level.

The integrated circuit (IC) automatically restarts the charge cycle when the battery falls below an internal threshold. If the input source is removed, the IC enters a high-impedance mode, preventing leakage from the battery to the input. Charge current is reduced when the die temperature reaches 120°C, protecting the device and PCB from damage.

The DIO59016 can operate as a boost regulator on command from the system. The boost regulator includes a soft-start that limits inrush current from the battery and uses the same external components used for charging the battery.

Applications

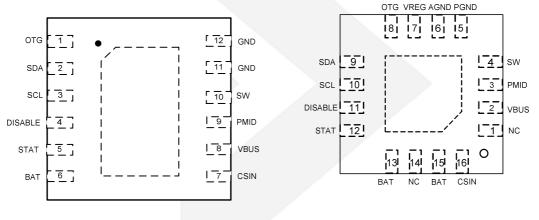
- Cell Phones, Smart Phones, PDAs
- Tablet, Portable Media Players
- Gaming Device, Digital Cameras



Ordering Information

Order Part Number	Top Marking		TA	Package	
DIO59016CL16	59016	Green	-40 to 85°C	TQFN-16	Tape & Reel, 5000
DIO59016CD12	59016	Green	-40 to 85°C	DFN3*3-12	Tape & Reel, 5000

Pin Assignments



DFN3*3-12

TQFN3*3-16







Pin Definitions

Name	Description
VBUS	Charger Input Voltage and USB-OTG output voltage. Bypass with a 1µF capacitor to PGND.
NC	No Connect. No external connection is made between this pin and the IC's internal circuitry.
SCL	I ² C Interface Serial Clock. This pin should not be left floating.
PMID	Power Input Voltage. Power input to the charger regulator, bypass point for the input current sense, and high-voltage input switch. Bypass with a minimum of 10µF, 6.3V capacitor to PGND.
SDA	I ² C Interface Serial Data. This pin should not be left floating.
SW	Switching Node. Connect to output inductor.
STAT	Status. Open-drain output indicating charge status. The IC pulls this pin LOW when charging.
PGND	Power Ground. Power return for gate drive and power transistors. The connection from this pin to the bottom of CMID should be as short as possible.
OTG	On-The-Go. Enables boost regulator in conjunction with OTG_EN and OTG_PL bits (see Table 14).
CSIN	Charging current detection input terminal.
DISABLE	Charge Disable. If this pin is HIGH, charging is disabled. When LOW, charging is controlled by the I ² C registers.
VREG	Regulator Output. Connect to a 1μ F capacitor to PGND. This pin can supply up to 2mA of DC load current. The output voltage is PMID, which is limited to 1.8V.
BAT	Battery Voltage. Connect to the positive (+) terminal of the battery pack. Bypass with a 0.1μ F capacitor to PGND if the battery is connected through long leads.
GND	Power Ground.
AGND	Analog ground.



Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Rating" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

	Parameter	Rating	Unit	
	Continuous	-1.4 to 26.0	V	
VBUS Voltage	Pulsed, 100ms Maximum Non-Repetitive	-2.0 to 26.0	v	
STAT Voltage		-0.3 to 26.0	V	
PMID Voltage		6.5	V	
SW, CSIN, VBAT, DISABLE Vo	Itage	-0.3 to 6.5	v	
Voltage on Other Pins		-0.3 to 6.5	V	
Maximum V_{BUS} Slope above 5.5V when Boost or Charger are Active		4	V/µs	
ESD	НВМ	2000		
CDM		500	V	
Junction Temperature		-40 to 150	°C	
Storage Temperature		-65 to 150	°C	
Lead Soldering Temperature, 10) Seconds	260	°C	

Recommend Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended Operating conditions are specified to ensure optimal performance to the datasheet specifications. DIOO does not Recommend exceeding them or designing to Absolute Maximum Ratings.

Parameter	Rating	Unit	
Supply Voltage		4 to 6	V
Maximum Battery Voltage when Boost enabled	4.5	V	
Negative VBUS Slew Rate during VBUS Short	T _A ≤60°C	4)//uc
Circuit, C _{MID} ≤10µF	T _A ≥60°C	2	V/µs
Ambient Temperature		-30 to 85	°C
Junction Temperature		-30 to 120	°C



Electrical Characteristics

 V_{IN} = 5V, T_A = 25°C, unless otherwise specified.

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Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit	
Power Supp	blies						
		V _{BUS} >V _{BUS(min)} , PWM Switching		10		mA	
I _{VBUS}	VBUS Current	V _{BUS} > V _{BUS(min)} ; PWM Enabled, Not Switching (Battery OVP Condition); I_IN Setting=100 mA		0.2		mA	
		0°C <tj<85°c, hz_mode="1</td"><td></td><td>88</td><td></td><td>μA</td></tj<85°c,>		88		μA	
I _{LKG}	VBAT to VBUS Leakage Current	$0^{\circ}C < T_J < 85^{\circ}C, HZ_MODE=1,$ V _{BAT} =4.2V, V _{BUS} =0V		1.6	5.0	μA	
I _{BAT}	Battery is charge Current in	0°C <t<sub>J< 85°C, HZ_MODE=1, V_{BAT}=4.2V</t<sub>		5	10	μA	
IBAT	High- Impedance Mode	DISABLE=1, 0°C <t<sub>J<85°C, V_{BAT}=4.2V</t<sub>	, 0°C <tj<85°c, 5<="" td=""><td>10</td><td>μΛ</td></tj<85°c,>		10	μΛ	
Charger Vo	oltage Regulation						
	Charge Voltage Range		4.2		4.4	V	
V _{OREG}	Charge Voltage Accuracy	T _A =25°C	-0.5%		0.5%		
	Charge Voltage Accuracy	T _J =0 to 125°C	-1%		1%		
Charging C	Current Regulation						
	Output Charge Current Range	$V_{SHORT} < V_{BAT} < V_{OREG},$ $R_{SENSE} = 68 m \Omega$	550		1500	mA	
I _{OCHRG}	Charge Current Accuracy	$20mV \le V_{IREG} \le 40mV$	-7		7	%	
	Across R _{SENSE}	V _{IREG} >40mV	-4		4	%	
Logic Leve	Is: DISABLE, SDA, SCL, OTG						
VIH	High-Level Input Voltage		1.05			V	
V _{IL}	Low-Level Input Voltage				0.4	V	
I _{IN}	Input Bias Current	Input Tied to GND or V _{IN}		0.01	1.00	μA	
Charge Ter	mination Detection						
	Termination Current Range	V_{BAT} > V_{OREG} - V_{RCH} , R_{SENSE} = 68 m Ω	50		400	mA	
	Termination Current Accuracy	$[V_{CSIN} - V_{BAT}]$ from 6mV to 20mV	-25		25	%	
I _(TERM)	Termination Current Accuracy	[V _{CSIN} – V _{BAT}] from 20mV to 40mV	-10		10	%	
	Termination Current Deglitch Time			30		ms	
1.8V Linear	Regulator						
V _{REG}	1.8V Regulator Output	I _{REG} from 0 to 2mA	1.7	1.8	1.9	V	



DIO59016 Short-Circuit Current Limit 4.8 mΑ **Input Power Source Detection** To Initiate and Pass VBUS **VBUS Input Voltage Rising** 3.75 4 4.25 V VIN(MIN) Validation 0.3 V V_{hys} **VBUS** Validation Time 30 ms t_{VBUS} VALID Special Charger (VBUS) Special Charger Set point V_{SP} -3 3 % Accuracy **Input Current Limit** REG[7:6]=00 TBD 100 TBD REG[7:6]=01 470 500 530 Input Current Limit Threshold mΑ INLIM REG[7:6]=10 750 800 850 No limit REG[7:6]=11 **Battery Recharge Threshold Recharge Threshold** Below V(OREG) 50 200 mV V_{RCH} **Deglitch Time** V_{BAT} Falling Below V_{RCH} Threshold 30 ms **STAT Output** STAT Output Low I_{STAT}=10mA V 04 VSTAT(OL) μA ISTAT(OH) STAT High Leakage Current V_{STAT}=5V 1 **Sleep Comparator** Sleep-Mode Entry Threshold, 0.04 v VSLP $4V \leq V_{BAT} \leq V_{OREG}$, V_{BUS} Falling 0 0.1 VBUS- VBAT Sleep-Mode Exit Threshold, v $V_{\text{SLP-EXIT}}$ 01 V_{BUS}-V_{BAT} Deglitch Time for VBUS Rising **Rising Voltage** 30 ms t_{SLP EXIT} Above VBAT by VSLP **Power Switches** Q3 On Resistance(VBUS to I_{IN(LIMIT)}=500mA 86 PMID) $R_{\text{DS(ON)}}$ mΩ Q1 On Resistance(PMID to SW) 85 Q2 On Resistance(SW to GND) 75 **Charger PWM Modulator Oscillator Frequency** f_{SW} 1.7 2 2.3 MHz D_{MAX} Maximum Duty Cycle 100 % D_{MIN} Minimum Duty Cycle 6 %



I _{SYNC}	Synchronous to Non-Synchronous Current Cut-Off Threshold ⁽²⁾	Low-Side MOSFET(Q2) Cycle-by- Cycle Current Limit		300		mA	
Boost Mode	e Operation(OPA_MODE=1, HZ_M	ODE=0)					
	Depend Quite ut Voltage at VPLIS	2.5V < V_{BAT} <4.5V, I_{LOAD} from 0 to 200mA	4.88	5.15	5.25		
VBOOST	Boost Output Voltage at VBUS	$3.0V < V_{BAT} < 4.5V$, I_{LOAD} from 0 to $500mA$	4.85	5.15	5.25	V	
I _{BAT(BOOST)}	Boost Mode Quiescent Current	PFM Mode, V _{BAT} =3.6V, I _{OUT} =0		500		μA	
ILIMPK(BST)	Q2 Valley Current Limit		1200	1600	2000	mA	
	Minimum Battery Voltage for Boost	While Boost Active		2.6		M	
UVLO _{BST}	Operation	To Start Boost Regulator		2.7		V	
Battery Dete	ection		<u> </u>				
IDETECT	Battery Detection Sink Current ⁽¹⁾	Begins after Charge Termination Detected		-10		mA	
t _{DETECT}	Battery Detection Time			30		ms	
Protection a	and Timers		<u> </u>				
VELIS	VBUS Over-Voltage Shutdown	V _{BUS} Rising	5.82	6	6.2	V	
VBUS _{OVP}	Hysteresis	V _{BUS} Falling		200		mV	
I _{LIMPK(CHG)}	Q1 Cycle-by-Cycle Peak Current Limit	Charge Mode		3		A	
V	Battery Short-Circuit Threshold	V _{BAT} Rising		2		V	
V _{SHORT}	Hysteresis	V _{BAT} Falling		100		mV	
I _{SHORT}	Linear Charging Current	V _{BAT} <v<sub>SHORT</v<sub>		30		mA	
T	Thermal Shutdown Threshold	T_J Rising		145		°C	
T _{SHUTDWN} Hysteresis		TյFalling		10		ر 	
T _{CF}	Thermal Regulation Threshold	Charge Current Reduction Begins		120		°C	
t _{INT}	Detection Interval			30		ms	

Notes:

1. Negative current is current flowing from the battery to VBUS (discharging the battery).

2. Q2 always turn on for 60ns, then turns off if current is below $I_{\mbox{\scriptsize SYNC}}.$



I²C Timing Specifications

Guaranteed by design.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit	
		Standard Mode			100		
		Fast Mode			400	kHz	
f _{SCL}	SCL Clock Frequency	High-Speed Mode, $C_B \leq 100 pF$			3400		
		High-Speed Mode, C _B ≤400pF			1700		
	Bus-Free Time between STOP	Standard Mode		4.7			
t _{BUF}	and START Conditions	Fast Mode		1.3		μs	
		Standard Mode		4		μs	
t _{HD;STA}	t _{HD;STA} t _{HD;STA} Hold Time	Fast Mode		600		ns	
		High-Speed Mode		160		ns	
		Standard Mode		4.7		μs	
+	t _{LOW} SCL LOW Period	Fast Mode		1.3		μs	
LOW	SCE LOW Period	High-Speed Mode, $C_B \leq 100 pF$		160		ns	
		High-Speed Mode, $C_B \leq 400 pF$		320		ns	
	SCL HIGH Period	Standard Mode		4		μs	
		Fast Mode		600		ns	
t _{HIGH}		High-Speed Mode, $C_B \leq 100 pF$		60		ns	
		High-Speed Mode, $C_B \leq 400 pF$		120		ns	
		Standard Mode		4.7		μs	
t _{SU;STA}	Repeated START Setup Time	Fast Mode		600		ns	
		High-Speed Mode		160		ns	
		Standard Mode		250			
t _{SU;DAT}	Data Setup Time	Fast Mode		100		ns	
		High-Speed Mode		10			
		Standard Mode	0		3.45	μs	
+	Data Hold Time	Fast Mode	0		900	ns	
t _{hd;dat}		High-Speed Mode, $C_B \leqslant 100 pF$	0		70	ns	
		High-Speed Mode, $C_B \leqslant 400 pF$	0		150	ns	
		Standard Mode	20+	0.1C _B	100	-	
t _{RCL}	SCL Rise Time	Fast Mode	20+	0.1C _B	300		
	SCL Rise Time	High-Speed Mode, $C_B \leq 100 pF$		10	80	ns	
		High-Speed Mode, $C_B \leqslant 400 pF$		20	160		
		Standard Mode	20+	0.1C _B	300		
terri	SCL Fall Time	Fast Mode	20+0.1C _B 300		300	ne	
t _{FCL}		High-Speed Mode, $C_B \leqslant 100 pF$		10	40	ns	
		High-Speed Mode, $C_B \leq 400 pF$		20	80		



	SDA Rise Time	Standard Mode	20+	0.1C _B	300	
t _{RDA}	Rise Time of SCL after a	Fast Mode	20+0.1C _B		300	
t _{RCL1}	Repeated START Condition and	High-Speed Mode, $C_B \leq 100 pF$		10	80	ns
	after ACK Bit	High-Speed Mode, C _B ≪400pF		20	160	
t _{FDA} SDA Fall		Standard Mode	20+0.1C _B		300	
	SDA Fall Time	Fast Mode	20+0.1C _B		300	
		High-Speed Mode, C _B ≤100pF		10	80	ns
		High-Speed Mode, C _B ≪400pF		20	160	
		Standard Mode		4		μs
t _{su;sto}	Stop Condition Setup Time	Fast Mode		600		ns
		High-Speed Mode		160		ns
C _B	Capacitive Load for SDA, SCL				400	pF

Timing Diagrams

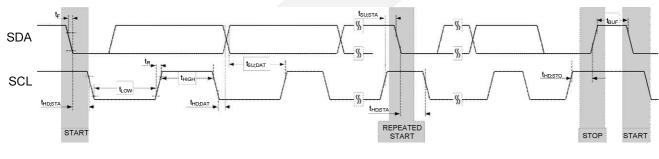
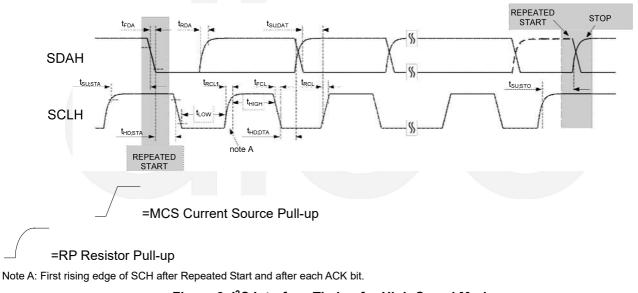
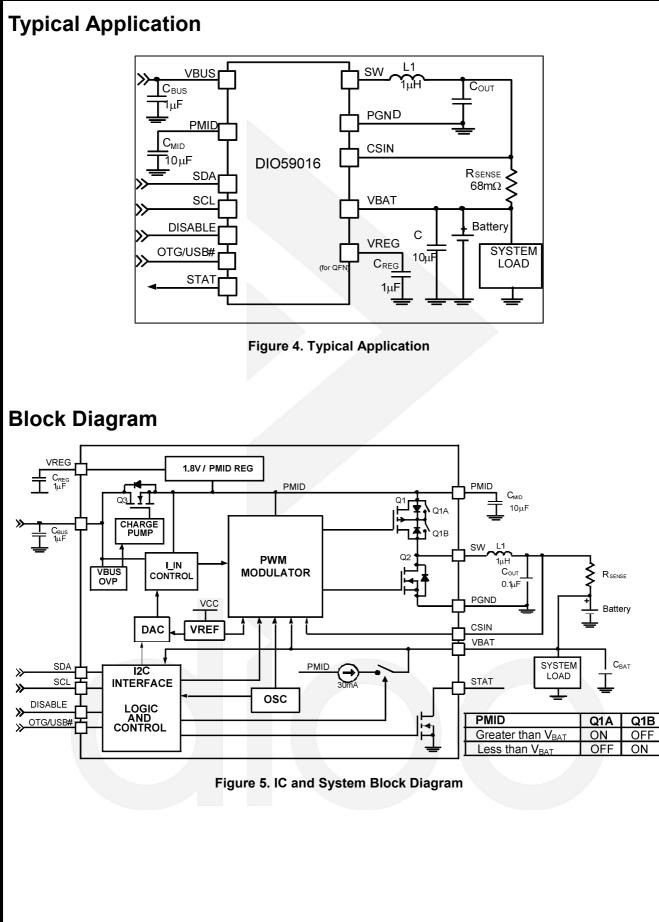


Figure 2. I²C Interface Timing for Fast and Slow Modes



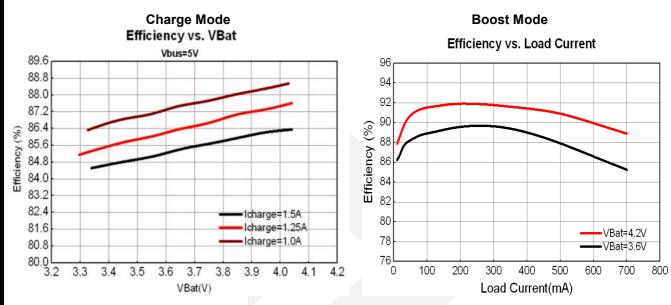






Typical Performance Characteristic

Typical value: $T_A = 25^{\circ}C$, $V_{IN}=5V$, unless otherwise specified.

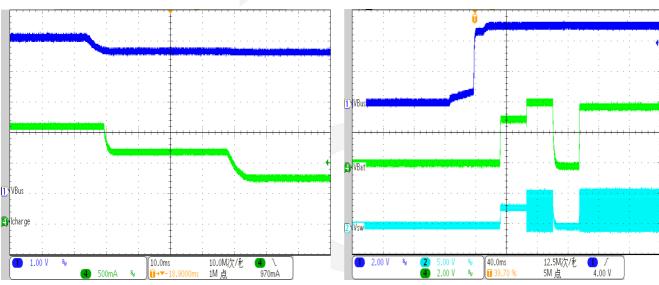


Charge Mode Typical Characteristics

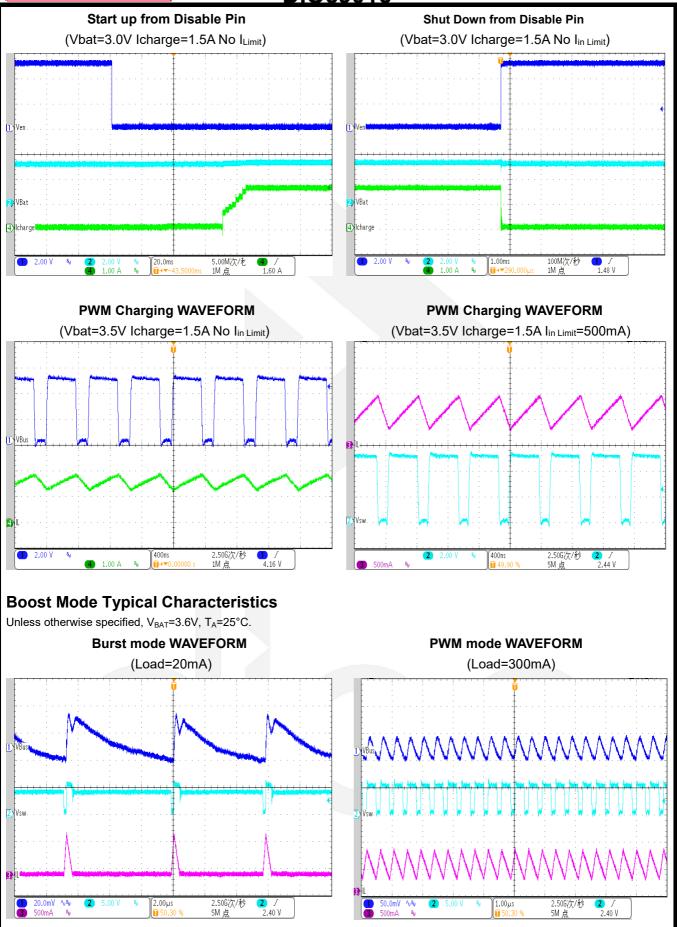
Unless otherwise specified, V_{OREG} =4.2V, V_{BUS} =5.0V, and T_A =25°C.



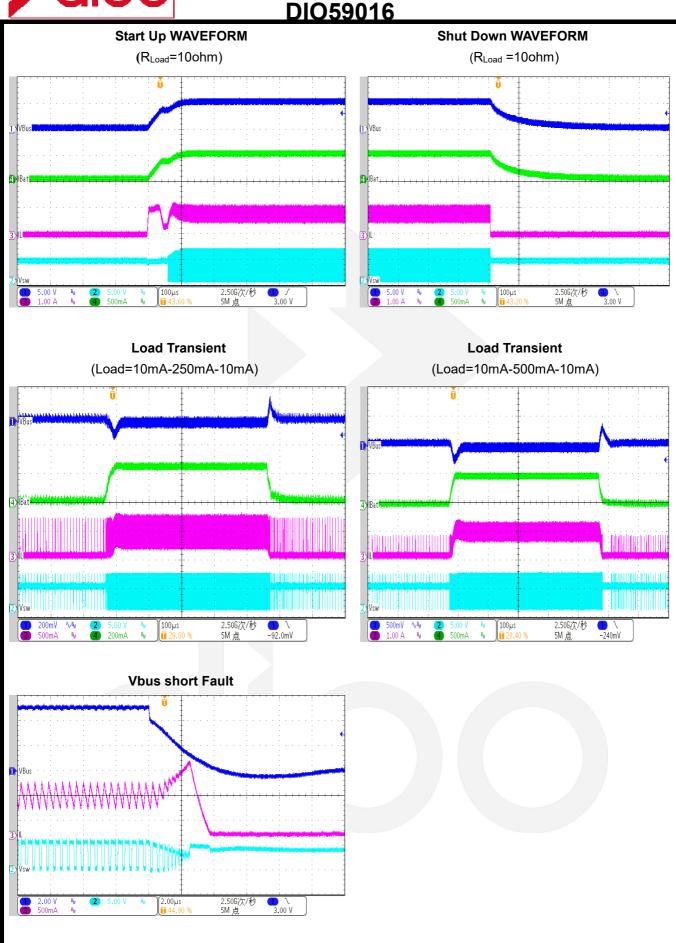
No Battery at VBUS Power-up













Application Information

Circuit Description/Overview

When charging batteries with a current-limited input source, such as USB, a switching charger's high efficiency over a wide range of output voltages minimizes charging time.

DIO59016 combines a highly integrated synchronous buck regulator for charging with a synchronous boost regulator, which can supply 5V to USB On-The-Go (OTG) peripherals. The regulator employs synchronous rectification for both the charger and boost regulators to maintain high efficiency over a wide range of battery voltages and charge states.

The DIO59016 has three operating modes:

- 1. Charge Mode:
- Charge a signal-cell Li-ion or Li-polymer battery.
- 2. Boost Mode:

Provides 5V power to USB-OTG with an integrated synchronous rectification boost regulator using the battery as input.

3. High-Impedance Mode:

Both the boost and charging circuits are OFF in this mode. Current flow from VBUS to the battery or from the battery to VBUS is blocked in this mode. This mode consumers very little current from VBUS or the battery.

Charge Mode

In charge Mode, DIO59016 employs four regulation loops:

- 1. Input Current: Limits the amount of current drawn from VBUS. This current is sensed internally and can be programmed through the I²C interface.
- 2. Charging Current: Limits the maximum charging current. This current is sensed using an external R_{SENSE} resistor.
- 3. Charge Voltage: The regulator is restricted from exceeding this voltage. As the internal battery voltage roses, the battery's internal impedance and R_{SENSE} work in conjunction with the charge voltage regulation to decrease the amount of current flowing to the battery. Battery charging is completed when the voltage across R_{SENSE} drops below the I_{TERM} threshold.
- 4. Temperature: If the IC's junction temperature reaches 120℃,charge current is reduced until the IC's temperature stabilizes at 120℃.
- 5. An additional loop limits the amount of drop on VBUS to a programmable voltage (V_{SP}) to accommodate "special chargers" that limit current to a lower current than might be available from a "normal" USB wall charger.

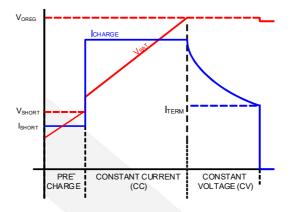
Battery Charging Curve

If the battery voltage is below V_{SHORT}, a linear current source pre-charges the battery until V_{BAT} reaches V_{SHORT}. The PWM charging circuit is then started and the battery is charged with a constant current if sufficient input power is available. The current slew rate is limited to prevent overshoot.

The DIO59016 is designed to work with a current-limited input source at VBUS. During the current regulation phase of charging, I_{INLIM} or the programmed charging current limits the current available to charge the battery and



power the system. The effect of I_{INLIM} on I_{CHARGE} can be see in Figure 7.





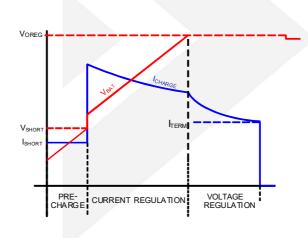


Figure 7. Charge Curve, IINLIM Limits ICHARGE

Assuming that V_{OREG} is programmed to the cell's fully charged "float" voltage, the current that the battery accepts with the PWM regulator limiting its output (sensed at VBAT) to V_{OREG} declines, and the charger enters the voltage regulation phase of charging. When the current declines to the programmed I_{TERM} value, the charge cycle is complete. Charge current termination can be disabled by resetting he TE bit (REG[3]).

The charger output or "float" voltage can be programmed by the OREG bits from 4.2V to 4.44V in 20mV increments, as shown in Table 1.

Decimal	Hex	VOREG
0~35	00~23	4.20
36~40	24~28	4.30
41~43	29~2B	4.35
44~62	2C~3E	4.40

The following charging parameters can be programmed by the host through I^2C .



Table 2. Programmable Charging Parameters

Parameter	Name	Register
Output Voltage Regulation	V _{OREG}	REG2[7:2]
Battery Charging Current Limit	I _{OCHRG}	REG4[6:4]
Input Current Limit	I _{INLIM}	REG1[7:6]
Charge Termination Limit	I _{TERM}	REG4[2:0]

A new charge cycle begins when one of the following occurs:

- The battery voltage falls below Voreg-Vrch
- VBUS Power on Reset (POR) clears and the battery voltage is below the V_{SHORT}.
- CE or HZ_MODE is rest through I²C write to CONTROL1 (Reg1) register.

Charge Current Limit (I_{OCHARGE})

Table 3. I_{OCHARGE} (REG4 [6:4]) Current as Function of I_{OCHARGE} Bits and R_{SENSE} Resistor Values

DEC	BIN	HEX	VRSENSE	I _{OCHARGE} (mA)	
DEC	DIN		(mV)	68mΩ	100mΩ
0	000	00	37.5	551	375
1	001	01	44.4	653	444
2	010	02	51.2	753	512
3	011	03	57.5	846	575
4	100	04	71.3	1048	713
5	101	05	78.1	1149	781
6	110	06	91.9	1351	919
7	111	07	101.8	1498	1018

Table 4. V_{RCH} (REG7 [1:0]) Recharge Voltage

DEC	BIN	HEX	VRCH	
DEC	DIN		(mV)	
0	00	00	50	
1	01	01	100	
2	10	02	150	
3	11	03	200	

Termination Current Limit

Current charge termination is enabled when TE (REG1[3])=1. Typical termination current values are given in Table 5.



Table 5. ITERM Current as Function of ITERM Bits (REG4[2:0]) and RSENSE Resistor Values

	VRSENSE	I _{TERM} (mA)	
ITERM	(mV)	68mΩ	100mΩ
0	3.1	46	31
1	6.3	92	63
2	9.4	138	94
3	12.5	184	125
4	15.6	230	156
5	18.8	276	188
6	21.9	322	219
7	25	368	250

When the charge current falls below I_{TERM}, PWM charging stops and the STAT bits change to READY (00) for about 30ms while the IC determines whether the battery and charging source are still connected. STAT then changes to CHARGE DONE (10), provided the battery and charger are still connected.

PWM Controller in Charge Mode

The IC uses a current-mode PWM controller to regulator the output voltage and battery charge currents. The synchronous rectifier (Q2) has a current limit that which off the FET when the current is negative by more than 300mA peak. This prevents current flow from battery.

V_{BUS} POR/Non-Compliant Charger Rejection

When the IC detects that VBUS has risen above $V_{IN(MIN)}$ (4.3V), the IC applies a 250 Ω load from VBUS to GND. To clear the VBUS POR (Power-On-Reset) and begin charging, VBUS must remain above $V_{IN(MIN)}$ and below VBUS_{OVP} for t_{VBUS_VALID} (30ms) before the IC initiates Charging. The VBUS validation sequence always occurs charging is initiated or re-initiated (for example, after a VBUS OVP fault or a V_{RCH} recharge initiation). t_{VBUS_VALID} ensures that unfiltered 50/60Hz chargers and other non-compliant chargers are rejected.

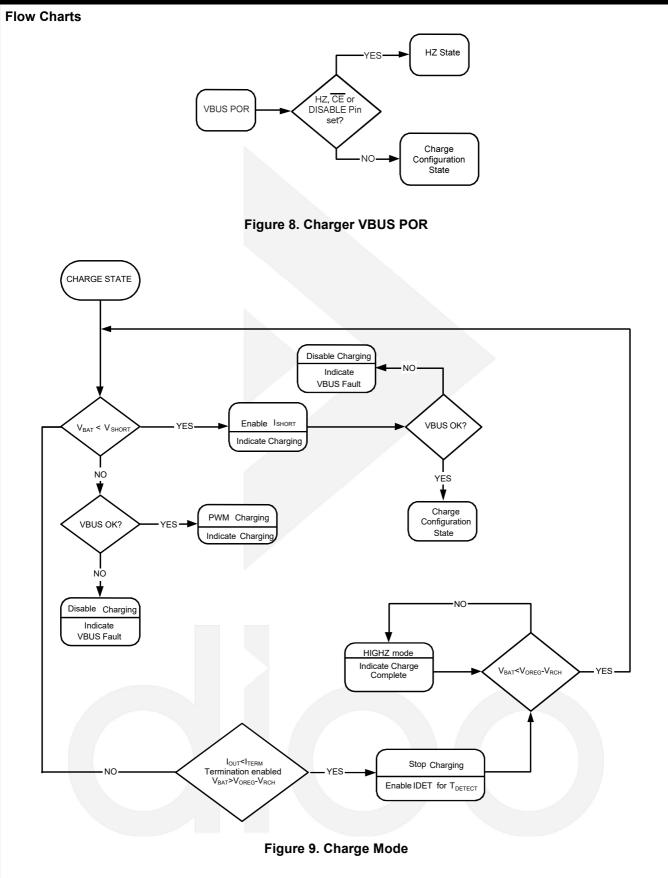
Input Current Limiting

To minimize charging time without overloading VBUS current limitations, the IC's input current limit can be programmed by the I_{INLIM} bits (REG1[7:6]).

IINLIM REG[7:6]	Input Current Limit		
00	100 mA		
01	500 mA		
10	800 mA		
11	No limit		

Table 6. Input Current Limit





Special Charger

The DIO59016 has additional functionality to limit input current in case a current-limited "special charger" is supplying VBUS. These slowly increase the charging current until either.

■ IINLIM or IOCHARGE is reached

■ V_{BUS}=V_{SP}.

If V_{BUS} collapses to V_{SP} when the current is ramping up, the DIO59016 charge with an input current that keeps $V_{BUS}=V_{SP}$. When the V_{SP} control loop is limiting the charge current, the SP bit (REG5[4]) is set.

DEC	BIN	HEX	V _{SP}
0	000	00	4.225
1	001	01	4.300
2	010	02	4.375
3	011	03	4.450
4	100	04	4.525
5	101	05	4.600
6	110	06	4.675
7	111	07	4.750

Table 7. V_{SP} as Function of SP Bits (REG5[2:0])

Thermal Regulation and Protection

When the IC's junction temperature reaches T_{CF} (about 120°C), the charger reduces its output current to 550mA to prevent overheating. If the temperature increases beyond $T_{SHUTDOWN}$; charging is suspended, the FAULT bits are set to 101, and STAT is pulsed HIGH. In Suspend Mode, all timers stop and the state of the IC's logic is preserved. Charging resumes at programmed current after the die cools to about 120°C.

Additional θ_{JA} data points, measured using the DIO59016 evaluation board, are given in Table 8 (measured with TA=25°C). Note that as power dissipation increases, the effective θ_{JA} decreases due to the larger difference between the die temperature and ambient.

Power (W)	θյΑ
0.504	54°C/W
0.844	50°C/W
1.506	46°C/W

Table 8. Evaluation Board Measured θ_{JA}

Charge Mode Input Supply Protection

Sleep Mode

When V_{BUS} falls below V_{BAT}+V_{SLP}, and V_{BUS} is above V_{IN(MIN)}. the IC enters Sleep Mode to prevent the battery from draining into VBUS. During Sleep Mode, reverse current is disabled by body switching Q1.

Input Supply Low-Voltage Detection

The IC continuously monitors VBUS during charging. If V_{BUS} falls below $V_{IN(MIN)}$, the IC:

- 1. Terminates charging.
- 2. Pulses the STAT pin, sets the STAT bits to 11, and sets the FAULT bits to 011.

If V_{BUS} recovers above the $V_{IN(MIN)}$ rising threshold after time t_{INT} (about two seconds), the charging process is repeated. This function prevents the USB power bus from collapsing or oscillating when the IC is connected to a suspended USB port or a low-current-capable OTG device.



Input Over-Voltage Detection

When the V_{BUS} exceeds VBUS_{OVP}, the IC:

- 1. Turns off Q3
- 2. Suspends charging
- 3. Sets the FAULT bits to 001, sets the STAT bits to 11, and pulses the STAT pin.

When V_{BUS} falls about 150mV below VBUS_{OVP}, the fault is cleared and charging resumes after V_{BUS} is revalidated (see VBUS POR/Non-Compliant Charger Rejection).

VBUS Short While Charging

If VBUS is shorted with a very low impedance while the IC is charging with $II_{NLIMIT}=100$ mA, the IC may not meet datasheet specifications until power is removed. To trigger this condition, V_{BUS} must be driven from 5V to GND with a high slew rate. Achieving this slew rate requires a 0Ω short to the USB cable less than 10cm from the connector.

Charge Mode Battery Detection & Protection

VBAT Over-Voltage Protection

The OREG voltage regulation loop prevents V_{BAT} from overshooting the OREG voltage when the battery is removed. When the PWM charger runs with no battery, the TE bit is not set and a battery is inserted that is charged to a voltage higher than V_{OREG} ; PWM pulses stop. If no further pulses occur for 30ms, the IC sets the FAULT bits to 100, sets the STAT bits to 11, and pulses the STAT pin.

Battery Detection During Charging

The IC can detect the presence, absence. During normal charging, once VBAT is close to VOREG and the termination charging, once VBAT is close to VOREG and the termination charge current is detected, the IC terminates charging and sets the STAT bits to 10. It then turns on a discharge current, IDETECT, for tDETECT. If VBAT is still above 2V, the battery is present and the IC sets the FAULT bits to 000. If VBAT is below 2V, the battery is absent and the IC:

- 1. Operation with No Battery
- 2. Sets the FAULT bits to 111.

Battery Short-Circuit Protection

If the battery voltage is below the short-circuit threshold (V_{SHORT}); a linear current source, I_{SHORT}, supplies V_{BAT} until V_{BAT}>V_{SHORT}.

System Operation with No Battery

The DIO59016 continues charging after VBUS POR with the default parameters, regulating the V_{BAT} line to 3.78V (if set V_{OREG} at 4.2V). In this way, the DIO59016 can start the system without a battery. Re-connect power to VBUS or reset ENN pin, IC can exit No Battery Mode.

Charger Status/Fault Status

The STAT pin indicates the operating condition of the IC and provides a fault indicator for interrupt driven systems.



Table 9. STAT Pin Function

EN_STAT	Charge State	STAT Pin
X	No Charging	OPEN
1	Charging	LOW
x	Fault	2Hz Pulse

The FAULT bits (Reg0[2:0]) indicate the type of fault in Charge Mode (see Table 10).

Table 10. Fault Status	Bits During	Charge Mode
------------------------	--------------------	-------------

i	Fault Bit		Foult Description
B2	B1	B0	Fault Description
0	0	0	Normal (No Fault)
0	0	1	VBUS OVP
0	1	0	Sleep Mode
0	1	1	Poor Input Source
1	0	0	Battery OVP
1	0	1	Thermal Shutdown
1	1	0	N.A
1	1	1	No Battery

Charge Mode Control Bits

Setting either HZ_MODE or \overline{CE} through I²C disables the charger and puts the IC into High-Impedance Mode.

Table 11. DISABLE Pin and CE Bit Functionality				
Charging	DISABLE Pin	CE	HZ_MODE	
ENABLE	0	0	0	
DISABLE	x	1	Х	
DISABLE	х	Х	1	
DISABLE	1	Х	Х	

Operational Mode Control

OPA_MODE (REG1[0]) and the HZ_MODE (REG1[1]) bits in conjunction with the FAULT state define the operational mode of the charger. Before VBUS connected to power source, IC should enter charge mode.

OPA_MODE	FAULT	Operation Mode			
0	0	Charge			
х	1	No charging			
1	0	Boost			
X	Х	High Impedance			
	•				

 Table 12. Operation Mode Control

Boost Mode

Boost Mode can be enabled if OTG pin and OPA_MODE bits as indicated in Table 13. The OTG pin ACTIVE state is 1 if OTG_PL=1 and 0 when OTG_PL=0.

If boost is active using the OTG pin, Boost Mode is initiated even if the HZ_MODE=1. The HZ_MODE bit overrides the OPA_MODE bit.



Table 13 Enabling Boost

Table 13. Enabling boost					
OTG_EN	OTG Pin	HZ_MODE	OPA_MODE	BOOST	
1	ACTIVE	Х	Х	Enabled	
Х	Х	0	1	Enabled	
Х	ACTIVE	Х	0	Disabled	
0	Х	1	Х	Disabled	
1	ACTIVE	1	1	Disabled	
0	ACTIVE	0	0	Disabled	

Boost COT Control

The IC uses a constant on-time and valley current detect to regulate VBUS. The regulator achieves excellent transient response by employing current-mode modulation. This technique causes the regulator to exhibit a load line. During COT Mode, the output voltage drops slightly as the input current rises. With a constant VBAT, this appears as a constant output resistance.

The "droop" caused by the output resistance when a load is applied allows the regulator to respond smoothly to load transient with no undershoot from the load line. This can be seen in and Figure 10

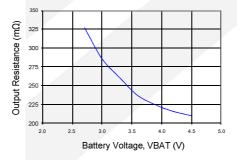


Figure 10. Output Resistance (Rout)

 V_{BUS} as a function of I_{LOAD} can be computed when the regulator is in PWM Mode (continuous conduction) as:

VOUT=5.15-ROUT ·ILOAD EQ.1 At VBAT=3.3V, and ILOAD=200mA, VBUS would drop to:

> Vout=5.15-0.26.0.2=5.098V EQ.1A

At V_{BAT}=2.7V, and I_{LOAD}=200mA, V_{BUS} would drop to:

EQ.1B Vout=5.15-0.327.0.2=5.085V

PFM Mode

If VBUS>VREFBOOST (nominally 5.07V) when the valley current comes to 0, the regulator enters PFM Mode. Boost pulses are inhibited until VBUS<VREFBOOST. Once VBUS<VREFBOOST, boost pulses are allowed for one or several times until VBUS>VREFBOOST. Therefore the regulator behaves like a burst mode regulator, with the average of its output voltage ripple at 5.07V in PFM Mode.

Table 14. Boost PWM Operating States				
Mode	Description	Invoked When		
LIN	Linear Startup	V _{BAT} >V _{BUS}		
SS	Boost Soft-Start	V _{BUS} <v<sub>BST</v<sub>		
BST	Reast Operation Made	$V_{\text{BAT}} \text{>} \text{UVLO}_{\text{BST}}$ and SS		
DOT	Boost Operation Mode	Completed		



Startup

When the boost regulator is shut down, current flow is prevented from V_{BAT} to V_{BUS} , as well as reverse flow from V_{BUS} to V_{BAT} .

LIN State

When EN rises, if V_{BAT}>UVLO_{BST}, the regulator attempts to bring PMID within 200mV of VBAT using an internal 450mA current source from VBAT (LIN State). If PMID has not achieved V_{BAT}- 200mV after 500µs, a FAULT state is initiated.

SS State

When PMID>V_{BAT}-200mV, the boost regulator begins switching with a SS modulator. The output slews up slowly and smoothly until V_{BUS} =VREF_{BOOST}.

If the output fails to achieve set point (VBST) within SS time, normally 128µs, a fault state is initiated.

BST State

This is the normal operating mode of the regulator. The regulator uses a constant on-time and valley current detect modulation scheme. The minimum t_{ON} is proportional to $\frac{V_{OUT} - V_{IN}}{V_{OUT}}$, which keeps the regulator's switching

frequency reasonably constant in CCM.

To ensure the VBUS does not pump significantly above the regulation point, the boost switch remains off as long as $FB>V_{REF}$.

Boost Faults

If a Boost FAULT OCCURS:

- 1. OPA_MODE bit is reset.
- 2. The power stage is in High-Impedance Mode.
- 3. The FAULT bits (REG0[2:0]) are set per Table 15.

Restart After Boost Faults

If boost was enabled with the OPA_MODE bit and OTG_EN=0, Boost Mode can only be enabled through subsequent I²C commands since OPA_MODE is reset on boost faults. If OTG_EN=1 and the OTG pin is still ACTIVE (see Table 13), the boost restarts after a 5.2ms delay, as shown in Figure 11. If the fault condition persists, restart is attempted every 10ms until the fault clears or an I²C command disables the boost.



DIO59016 Table 15. Fault Bits During Boost Mode

	-		T dalt Bits Baring Boost mode				
I	Fault Bi	t	Foult Description				
B2	B1	B0	Fault Description				
0	0	0	Normal (no fault)				
0	0	1	V _{BUS} >VBUS _{OVP}				
			VBUS fails to achieve the voltage required to				
0	0 1	0	advance to the next state during soft-start or				
0		U	sustained (>50µs) current limit during the BST				
			state.				
0	1	1	N/A: This code does not appear.				
1	0	0	N/A: This code does not appear.				
1	0	1	Thermal shutdown				
1	1	0	N/A: This code does not appear.				
1	1	1	N/A: This code does not appear.				



Figure 11. Boost Response Attempting to Start into VBUS Short Circuit (Times in µs)

VREG Pin

The 1.8V regulated output on this pin can be disabled through I²C by setting the DIS_VREG bit (REG5[6]). VREG can supply up to 2mA. This circuit, which is powered from PMID, is enabled only when PMID>VBAT and does not drain current from the battery. During boost, VREG is off. It is also off when the HZ_MODE bit (REG1[1])=1.

Monitor Register (Reg10H)

Additional status monitoring bits enable the host processor to have more visibility into the status of the IC. The monitor bits are real-time status indicators.

I²C Interface

The DIO59016's serial interface is compatible with Standard, Fast, Fast Plus, and High-Speed Mode I2C-Busspecifications.TheSCLlineisaninputandtheSDAlineisabi-directional open-drain output; it can only pull down the bus when active. The SDA line only pulls LOW during data reads and signaling ACK. All data is shifted in MSB (bit 7) first.

Slave Address

	l i	able 1	6. I ² C	Slave	Addre	ss By	e	
Part Type	7	6	5	4	3	2	1	0
DIO59016	1	1	0	1	0	1	0	R/W

In hex notation, the slave address assumes a 0LSB. The hex slave address for the DIO59016 is D4H and is D6H for all other parts in the family.



Bus Timing

As shown in Figure 12, data is normally transferred when SCL is LOW. Data is clocked in on the rising edge of SCL. Typically, data transitions shortly at or after the falling edge of SCL to allow ample time for the data to set up before the next SCL rising edge.

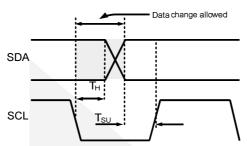


Figure 12. Data Transfer Timing

Each bus transaction begins and ends with SDA and SCLHIGH.A transaction begins with a START condition, which is defined as SDA transitioning from 1 to 0 with SCLHIGH, as shown in Figure 13.

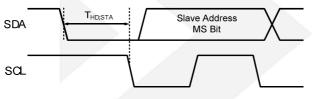
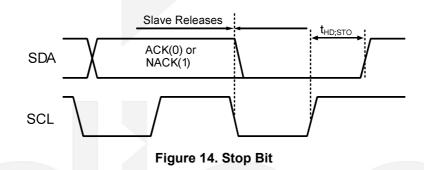


Figure 13. Start Bit

A transaction ends with a STOP condition, which is defined as SDA transitioning from 0 to 1 with SCL HIGH, as shown in Figure 14.



During a read from theDIO59016(Figure 16,Figure 17), the master issues a Repeated Start after sending the register address and before resending the slave address. The Repeated Start is a 1-to-0transition on SDA while SCL is HIGH, as shown in Figure 15.

High-Speed (HS) Mode

The protocols for High-Speed(HS), Low-Speed(LS), and Fast-Speed(FS) Modes are identical except the bus speed for HS Mode is 3.4MHz. HS Mode is entered when the bus master sends the HS master code 00001XXX after a start condition. The master code is sent in Fast or Fast Plus Mode (less than1MHz clock); slaves do not ACK this transmission.

The master then generates a repeated start condition (Figure 15) that causes all slaves on the bus to switch to HS Mode. The master then sends I²C packets, as described above, using the HS Mode clock rate and timing.



The bus remains in HS Mode until a stop bit (Figure14) is sent by the master. While in HS Mode, packets are separated by repeated start conditions (Figure 15).

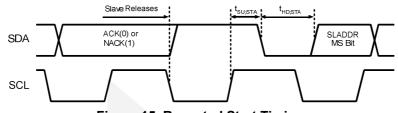


Figure 15. Repeated Start Timing

Read and Write Transactions

Master Drives Bus

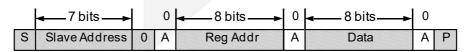
The figure below outline the sequences for data read and write. Bus control is signified by the shading of the

packet, defined as

and Slave Drive Bus

Table 17. Bit Definitions for Figure 16, Figure 17

Symbol	Definition
S	START, see Figure 13
А	ACK. The slave drives SDA to 0 to acknowledge the
	preceding packet.
Ā	NACK. The slave sends a 1 to NACK the preceding packet.
R	Repeated START, see Figure 15
Р	STOP, see Figure 14.





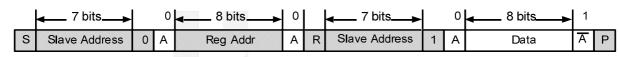


Figure 17. Read Transaction

. All addresses and data are MSB first.



Register Bit Definitions

1 CONTRO	DL0 Registe	r (0x00) Default Value=X1X	XOXXX	<u> </u>				•	
Bit	Bit 7	Bit 6	Bit	Bit	Bit 3	Bit 2	Bit 1	Bit 0	
NAME	Reserved	EN_STAT	ST	AT	BOOST	FAULT			
R/W	R/W	R/W	F	२	R	R			
			F	R harge / harge gress harge		to advance to th	R le: No Fault) VP ode ut Source OVP Shutdown ry : no fault)	ng soft-start or	
						011 = VBAT <u 100 = N/A: This 101 = Thermal</u 	code does not a	ppear.	
							code does not a code does not a		

2 CONTROL1 Register (0x01) Default Value=0011 0000 (30h)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME	I _{INLIM}		Reserved R/W Unused		TE	CE	HZ_MODE	OPA_MODE
R/W	R/V	V	R/	W	R/W	R/W	R/W	R/W
	Input cur	rent	Unuse	d	0 :Disable charge current	0 :Charger	0:Not High-Impedance	0 :Charge
	limit:				termination.	enabled.	Mode.	Mode.
Functio	00:100 n	٦A			1 : Enable charge current	1 : Charger	1 : High-Impedance	1:Boost Mode.
n	01 :500 r	mA			termination.	disabled.	Mode.	
	10 :800 r	mA						
	11: No lii	mit						



3 OREG Re	gister (0x0)2) Defa	ult Value=	0000 1010	(0Ah)				
Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
NAME			OF	EG			OTG_PL	OTG_EN	
R/W			R	W			R/W	R/W	
	Charger o	output "float"	' voltage;			0 :OTG pin active LOW. 0 :			
Function	programm	hable from 4	.2 to 4.4V;	defaults to (000010 (4.2	1 : OTG pin active HIGH.	Disables OTG pin.		
FUNCTION	00 0000~	10 0011 : 4.	2V; 10 0	100~10 100	00:4.3V;		1 : Enables OTG pin.		
	10 1001~1	10 1011: 4.3	35V; 10 1	100~11 11	10: 4.4V;				

4 IC_INFO Register (0x03) Default Value=1001 0100 (94h)

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
NAME	F	Reserved			PN	1	REV			
R/W		R			R		R			
Functio	Identifies the I	C supplier.		Part nun	nber bits.		IC Revision, revision 1.X, where X is the			
n							decimal of these three bits.			

5 IBAT Register (0x04) Default Value=1000 1001 (89h)

UIBAI Ite								
Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME	Reserved		V(I _{ocharge})		Reserved			
R/W	R/W		R/W		R/W		R/W	
	0 =	Programs the n	naximum charge	current	Unused	Sets the curren	t used for chargi	ng termination
	Unused	000: 37.5mV;	001: 44.4mV;			000 : 3.1mV;	001: 6.3mV;	
		010: 51.2 mV;	011: 57.5 mV		000 : 3.1mV; 001: 6.3mV; 010: 9.4mV; 011: 12.5mV; 100: 15.6mV; 101: 18.8mV;			
Function		100: 71.3 mV;	101: 78.1 mV	;		100: 15.6mV;	101: 18.8mV;	
Function		110: 91.9 mV;	111: 101.8 m\	<i>I</i> ;		110: 21.9mV;	V(ITERM) R/W at used for charg 001: 6.3mV; 011: 12.5mV; 101: 18.8mV; 111: 25mV; current step (ITE);	
		The charge curre	ent step (I _{OCHARGE})	is calculated		The termination of	current step (I _{TER}	м) can be
		using:				calculated using:	V(ITERM) R/W tt used for charg 001: 6.3mV; 011: 12.5mV; 101: 18.8mV; 111: 25mV; current step (I _{TE}	
		I _{OCHARGE} = V(I	_{OCHARGE})/R _{SENSE} ;			$I_{\text{TERM}} = V(I_{\text{TERM}})$	_M)/ R _{SENSE} ;	

6 SP_CHARGER Register (0x05) Default Value=0X1X X100

Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NAME	Reserve	DIS_VREG	Reserve	SP	EN_LEVEL		VSP	
R/W	R/W	R/W	R/W	R	R		R/W	
	Unused	0 :1.8V regulator is	Unused	0 :Special charger is not	0 : DISABLE pin	Special ch	arger inpu	ıt
		ON.		active (V_{BUS} is able to stay	is LOW .	regulation	VSP	
Functio		1 : 1.8V regulator		above V _{SP}).	1 : DISABLE pin	000: 4.225	5V; 001: 4.	300V;
n		is OFF.		1 : Special charger has	is HIGH.	010: 4.375	5V; 011: 4.	450V;
		DFN-12: Default=1		been detected and $V_{\mbox{\scriptsize BUS}}$ is		100: 4.525	5V; 101: 4.	600V;
		QFN-16:		being regulated to V_{SP} .		110: 4.675	5V; 111: 4.	750V
		Default=0						



NAME Reserved Reserved Reserved Reserved Vecome RW R/W R/W R/W R/W R/W R/W Function Unused Unused Unused Unused Recharge voltage of Voeeg drops 00: 50mV; 01: 100mV; 10: 150mV; 11: 200mV MONITOR Register (0x10h) Bit Bit 7 Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 Bit 0 MAME Items_care Vast_care LINCHG T_120 Icwa Iaus Vaus_vauto CV NAME Items_care Vast_care R <th></th> <th></th> <th></th> <th></th> <th></th> <th></th> <th>29010</th> <th></th> <th></th> <th></th> <th></th> <th></th> <th></th>							29010						
NAME Reserved Reserved Reserved Reserved Vrecet RW RW R/W R/W R/W R/W R/W Function Unused Unused Unused Unused Recharge voltage of Voreeg drops 00: 50mV; 01: 100mV; 10: 150mV; 11: 200mV MONITOR Register (0x10h) Bit Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 Bit 0 MAME Interaction VEXT_COMP LINCHG T_120 Icrus Isus Vext_value CV NAME Interaction R	7 Register	(0x07)	Defa	ult Value=(0000 ()001 (01h)							
RW RW RW RW RW RW Function Unused Unused Unused Unused Recharge voltage of V _{GREG} drops 00: 50mV; 01: 100mV; 10: 150mV; 11: 200mV MONITOR Register (0x10h) Bit Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 Bit 0 MAME I теки, сме VBAT_CME LINCHG T_120 I сме I выs V выс, уацио CV RVW R	Bit	Bit 7	Bit 6	Bit 5		Bit 4		Bit 3	Bit 2		Bit 1		Bit 0
Unused Unused Unused Unused Recharge voltage of V _{ORED} drops 00: 50mV; 01: 100mV; 10: 150mV; 11: 200mV MONITOR Register (0x10h) Bit Bit 7 Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 Bit 0 NAME Iteration VBAT_CMP LINCHG T_120 IcHo Ieus Veus_value CV RW R R R R R R R R R R Function ITERM_COMP VBAT_CMP LINCHG T_120 IcHo Ieus Veus_value CV NAME ITERM_COMP R <th< th=""><th>NAME</th><th colspan="7">Reserved Reserved</th><th>rved</th><th></th><th>V</th><th>RCH</th><th></th></th<>	NAME	Reserved Reserved							rved		V	RCH	
Function 00: 50mV; 01: 100mV; 10: 150mV; 11: 200mV MONITOR Register (0x10h) Bit 1 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 Bit 0 NAME Iteram_come Vaar_come LINCHG T_120 Ione Isus Vaus_vaub CV RW R R R R R R R R Function Iteram_come: ITERM comparator output. 0: V _{CSIN} -V _{BAT} <v<sub>ITERM. 1: V_{CSIN}-V_{BAT}<v<sub>ITERM 1: V_{DSIN}-V_{BAT} R<</v<sub></v<sub>	R/W		R/W			R/W		R/	W		R	/W	
MONITOR Register (0x10h) Bit Bit 7 Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 Bit 0 NAME Increase VBAT_CMP LINCHG T_120 Icea Isus VBUS_VALLD CV RVW R <td></td> <td></td> <td>Unused</td> <td>I</td> <th></th> <th>Unused</th> <th></th> <td>Unu</td> <td>sed</td> <td>Rec</td> <th>harge voltage</th> <th>e of V_{OR}</th> <th>REG drops.</th>			Unused	I		Unused		Unu	sed	Rec	harge voltage	e of V _{OR}	REG drops.
MONITOR Register (0x10h) Bit Bit 7 Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 Bit 0 NAME Irem.cm VBAT_CMP LINCHG T_120 Ices Isus Vaus_valub CV RW R	Function									00:	50mV; 01	: 100m\	√;
Bit Bit 7 Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 Bit 0 NAME Image: Comparison of the										10:	150mV; 11	: 200m\	V
Bit Bit 7 Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 Bit 0 NAME Image: Comparison of the													
NAME Iterm_CMP VBAT_CMP LINCHG T_120 Iche Isus VBUS_VALID CV R/W R	8 MONITO	R Regis	<u>ter (0x10</u>	h)					_				
RW R	Bit	Bi	t 7	Bit 6		Bit 5	Bit 4	Bit 3	Bit	t 2	Bit 1		Bit 0
Function ITERM_CMP: ITERM comparator output. 0: V _{CSIN} -V _{BAT} <v<sub>ITERM. VBAT_CMP Output of VBAT comparator in charging mode, 0: V_{BAT} <v<sub>SHORT Output of VBAT comparator in charging mode, 0: V_{BAT} <v<sub>SHORT 1: V_{DAT} >V_{SHORT} LINCHG In charging mode _0: 30mA linear charger Not Enable; 1: 30mA linear charger Enable. T_120 Thermal regulation comparator 0: T_J <120°C; 1: T_J >120°C Icw6 In charging mode, 0: Charging Current Controlled by I_{CHARGE} Control Loop. I n charging mode, 0: Charging Current Controlled by I_{CHARGE} Control Loop. 1: Charging Current Not Controlled by I_{CHARGE} VBus In charging mode, 0: I_{BUS} Limiting Charging Current. 1: Charge Current Not Limited by I_{BUS} VBus_value When V_{BUS} >V_{BUS} Not Valid 1: V_{BUS} is Valid CV In charging mode. 0:Constant Current Charging. 1:Constant Voltage Charging.</v<sub></v<sub></v<sub>	NAME		N_CMP	V _{BAT_CM}	ИР	LINCHG	T_120	I _{CHG}	IBU	JS	V _{BUS_VA}	LID	cv
ITERM comparator output. 0: V _{CSIN} -V _{BAT} <v<sub>ITERM. 1: V_{CSIN}-V_{BAT}>V_{ITERM} V_{BAT_CMP} Output of VBAT comparator in charging mode, 0: V_{BAT}<v<sub>SHORT 1: V_{BAT}>V_{SHORT} LINCHG In charging mode _0: 30mA linear charger Not Enable; 1: 30mA linear charger Enable. T_120 Thermal regulation comparator 0: T_J<120°C; 1: T_J>120°C IcHG In charging mode, 0: Charging Current Controlled by I_{CHARGE} Control Loop. 1 : Charging Current Not Controlled by I_{CHARGE} Control Loop. Isus In charging mode,0: I_{BUS} Limiting Charging Current. 1: Charge Current Not Limited by I_{BUS} V_{BUS_VALID} When V_{BUS}-V_{BUS} Not Valid 1: V_{BUS} is Valid CV In charging mode. 0:Constant Current Charging. 1:Constant Voltage Charging.</v<sub></v<sub>	R/W	I	R	R		R	R	R	F	ł	R		R
Note: Register (0x10h) is for Charge mode only.		Outpu LINCH In cha T_120 Therm IcHG In charg Control IBUS In charg VBUS_VA When V CV	t of VBAT G rging mode nal regulati ging mode Loop. ging mode Loop.	e ,0: 30m/ on compara , 0: Chargin ,0: I _{в∪s} Limi 0:V _{в∪s} Not \	A linea ator C ng Curr ting Cl Valid	r charger Not Enab : TJ<120°C; 1: TJ rent Controlled by I harging Current. 1: 1: V _{BUS} is Valid	ole; 1: 30mA line >120°C _{CHARGE} Control L Charge Curren	ear charge .oop. 1 : C t Not Limit	r Enable. harging (ed by Ι _{Βυ}	Curren	t Not Control	led by I	CHARGE
	Note: Re	gister (0:	x10h) is fo	r Charge m	ode or	ıly.							
		<u> </u>											

PCB Layout Recommendations

Bypass capacitors should be placed as close to the IC as possible. In particular, the total loop length for CMID should be minimized to reduce overshoot and ringing on the SW, PMID, and VBUS pins. All power and ground pins must be routed to their bypass capacitors, using top copper whenever possible. Copper area connecting to the IC should be maximized to improve thermal performance if possible.



CONTACT US

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